Tool ID: 317
Tool Location: 107

Equipment Information Sheet

AJA Sputter Deposition - 2

Manager: Chris Martin 607-254-4855
Backup: Shilling Du 607-254-4907
Backup: Philip Schneider 607-254-4931

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY
USAGE RESTRICTIONS
SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 30 minutes

- Maximum 4 hr block reservations anytime
- Must leave a 4hr block between reservations
- Maximum 12 hours reserved in advance at any time

MATERIALS COMPATIBILITY CATEGORY

Tool Category 4: Glass and Metal Categories

Allowed	Not Allowed
Tool category 1/1E, 2, and 3 materials	
Silicon Based Substrates and Films	No CNF Class A metals
III/V compound Semiconductors	**No Exposed CNF Group B metals-** ***metals can be buried/covered with staff approval***
Glass Substrates	Cannot be used as an etch stop
PECVD and ALD Films	
Buried Class B Metals with approval	
Organic/Bio Materials prepped w/o Salt Buffers	
Cured organics and baked Photoresist	No High Vapor pressure materials

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No high vapor pressure substrates or films (ITO, Indium, Zinc, etc)

Last Updated: 10/20/2026